

AMENDMENTS TO THE CLAIMS

This listing of claims replaces all prior versions, and listings, of claims in the application.

1.-35. (Canceled)

36. (Currently Amended) A method for polishing a substrate comprising a metal in an oxidized form, the method comprising the steps of:

(a) providing a substrate comprising a metal in an oxidized form, wherein the metal is a noble metal selected from the group consisting of platinum, iridium, ruthenium, rhodium, palladium, silver, osmium, gold, and combinations thereof,

(b) contacting a portion of the substrate with a chemical-mechanical polishing system comprising:

(i) a polishing component selected from the group consisting of an abrasive, a polishing pad, and a combination thereof,

(ii) about 0.1 to about 1 wt.% of a reducing agent based on the weight of the liquid carrier and any components dissolved or suspended therein, wherein the reducing agent ~~is being selected from the group consisting of~~ 3-hydroxy-4-pyrones, α -hydroxy- γ -butyrolactones, ascorbic acid, borane, borohydrides, dialkylamine boranes, hydrogen, hydroquinones, hypophosphorous acid, trihydroxybenzenes, solvated electrons, sulfurous acid, salts thereof, and mixtures thereof, and

(iii) a liquid carrier, and

(c) abrading at least a portion of the metal in an oxidized form to polish the substrate.

37. (Currently Amended) The method of claim 36, wherein the chemical-mechanical polishing system comprises about 0.1 to about 0.5 wt.% ~~reducing agent~~ ascorbic acid based on the weight of the liquid carrier and any components dissolved or suspended therein.

38.-39. (Canceled)

41. (Previously Presented) The method of claim 36, wherein the polishing system has a pH of about 1 to about 7.

42.-43. (Canceled)

44. (New) The method of claim 41, wherein the chemical-mechanical polishing system has a pH of about 2 to about 5.

45. (New) The method of claim 36, wherein the oxidized form is selected from the group consisting of oxides, nitrides, borides, sulfides, and mixtures thereof.

46. (New) The method of claim 45, wherein the oxidized form is an oxide, and the metal in an oxidized form has a molecular formula M_xO_y in which M represents the metal and x and y represent integers, where y is greater than or equal to x.

47. (New) The method of claim 46, wherein the metal in an oxidized form is iridium oxide.

48. (New) The method of claim 36, wherein the chemical-mechanical polishing system comprises an abrasive suspended in the liquid carrier, and the abrasive comprises a metal oxide selected from the group consisting of alumina, silica, ceria, zirconia, titania, germania, co-formed products thereof, and combinations thereof.

49. (New) The method of claim 48, wherein the abrasive comprises silica, fumed alumina, or a combination thereof.

50. (New) The method of claim 48, wherein the abrasive comprises α -alumina.

51. (New) The method of claim 50, wherein the abrasive further comprises fumed alumina.

52. (New) The method of claim 50, wherein α -alumina comprises about 60 wt.% or more of the abrasive based on the total weight of the abrasive.

53. (New) The method of claim 51, wherein α -alumina comprises about 60 wt.% or more of the abrasive based on the total weight of the abrasive.

54. (New) The method of claim 36, wherein the chemical-mechanical polishing system further comprises a complexing agent.

55. (New) The method of claim 36, wherein the chemical-mechanical polishing system further comprises a pH buffering agent.

56. (New) The method of claim 36, wherein the chemical-mechanical polishing system further comprises a surfactant.

57. (New) The method of claim 36, wherein the liquid carrier is water.

58. (New) The method of claim 57, wherein the oxidized form is selected from the group consisting of oxides, nitrides, borides, sulfides, and mixtures thereof.

59. (New) The method of claim 58, wherein the oxidized form is an oxide, and the metal in an oxidized form has a molecular formula M_xO_y in which M represents the metal and x and y represent integers, where y is greater than or equal to x.

60. (New) The method of claim 59, wherein the metal in an oxidized form is iridium oxide.

61. (New) The method of claim 57, wherein the chemical-mechanical polishing system comprises an abrasive suspended in the liquid carrier, and the abrasive comprises a metal oxide selected from the group consisting of alumina, silica, ceria, zirconia, titania, germania, co-formed products thereof, and combinations thereof.

62. (New) The method of claim 61, wherein the abrasive comprises silica, fumed alumina, or a combination thereof.

63. (New) The method of claim 61, wherein the abrasive comprises α -alumina.

64. (New) The method of claim 63, wherein the abrasive further comprises fumed alumina.

65. (New) The method of claim 63, wherein α -alumina comprises about 60 wt.% or more of the abrasive based on the total weight of the abrasive.

66. (New) The method of claim 64, wherein α -alumina comprises about 60 wt.% or more of the abrasive based on the total weight of the abrasive.

67. (New) The method of claim 57, wherein the chemical-mechanical polishing system further comprises a complexing agent.

68. (New) The method of claim 57, wherein the chemical-mechanical polishing system further comprises a pH buffering agent.

69. (New) The method of claim 57, wherein the chemical-mechanical polishing system further comprises a surfactant.

70. (New) The method of claim 57, wherein the chemical-mechanical polishing system has a pH of about 2 to about 5.